


MDT0500D1OSC-PAR	800 x 480	Parallel Interface	TFT Module
(MCT050ACA0CW800480LML)			
Specification			
Version: 1		Date: 27/04/2019	
Revision			
1	25/04/2019	First issue	

Display Features			
Display Size	5.0"		
Resolution	800 x 480		
Orientation	Landscape		
Appearance	RGB		
Logic Voltage	3.1V		
Interface	Parallel		
Brightness	300 cd/m ²		
Touchscreen	CTP		
Module Size	120.70 x 75.80 x 9.68mm		
Operating Temperature	-20°C ~ +70°C		
Pinout	36 way connector		
Pitch	---		
		Box Quantity	Weight / Display
		---	---

* - For full design functionality, please use this specification in conjunction with the SSD1963 specification.(Provided Separately)

Display Accessories	
Part Number	Description
MDIB-RPI	The MDIB-RPI is a Raspberry Pi interface board designed to provide connectivity and compatibility to a range of MIDAS TFT displays.
MCFFC36WA50-1963 MCFFC36WA100-1963	36 way 100mm FFC with 0.5mm pitch

Optional Variants	
Appearances	Voltage

Summary

TFT 5.0" is a TN transmissive type color active matrix TFT liquid crystal display that use amorphous silicon TFT as switching devices. This module is a composed of a TFT_LCD module, It is usually designed for industrial application and this module follows RoHs,

General Specifications

- Size: 5.0 inch
- Dot Matrix: 800 × 3(RGB) × 480 dots
- Module dimension: 120.7 x 75.8 x 9.68 (Max) mm
- Active area: 108.0 x 64.8 mm
- Dot pitch: 0.045 x 0.135 mm
- LCD type: TFT, Normally White, Transmissive
- Aspect Ratio: 16:9
- Backlight Type: LED, Normally White
- Controller IC: SSD1963
- Interface: Digital 8080 family MPU 8bit/16bit
- CTP IC: FT5426DQ8 Or Equal
- CTP Interface: I2C
- CTP FW Version: 2
- With /Without TP: With CTP
- Surface: Glare

*Color tone slight changed by temperature and driving voltage.



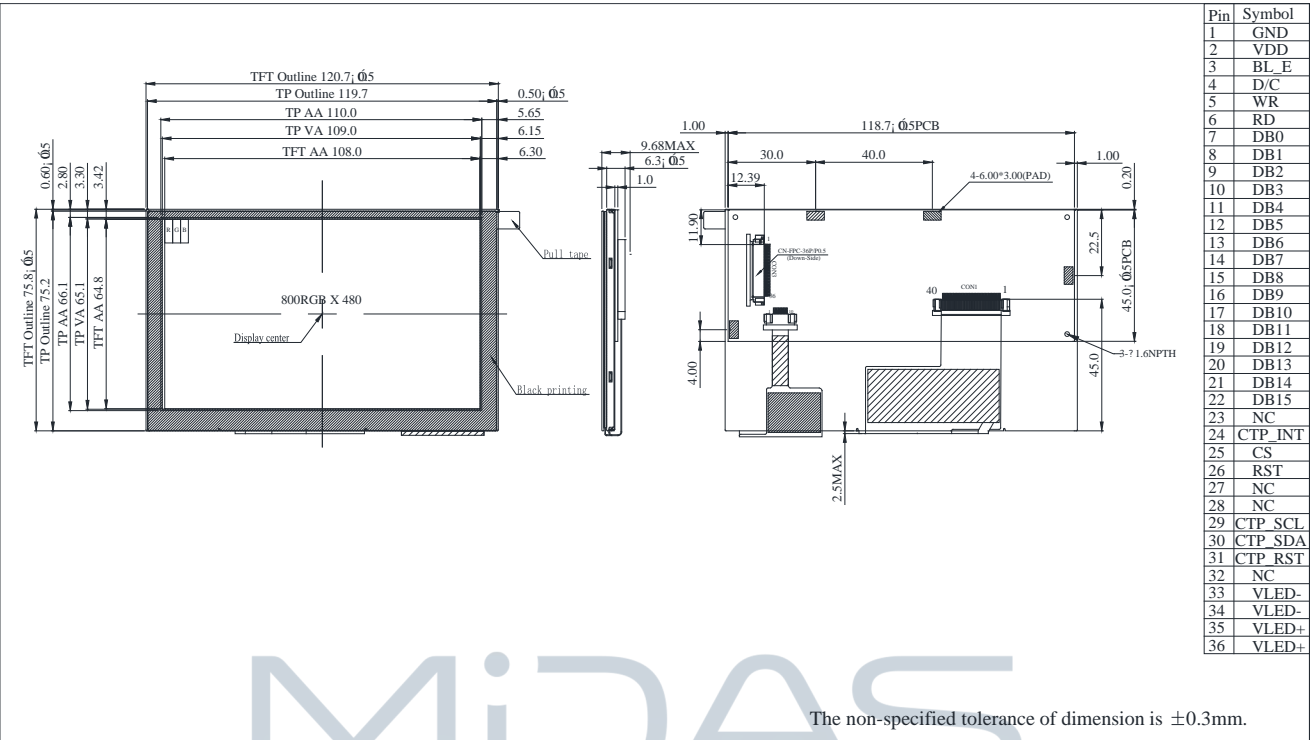
Interface

LCM PIN Definition (CON3)

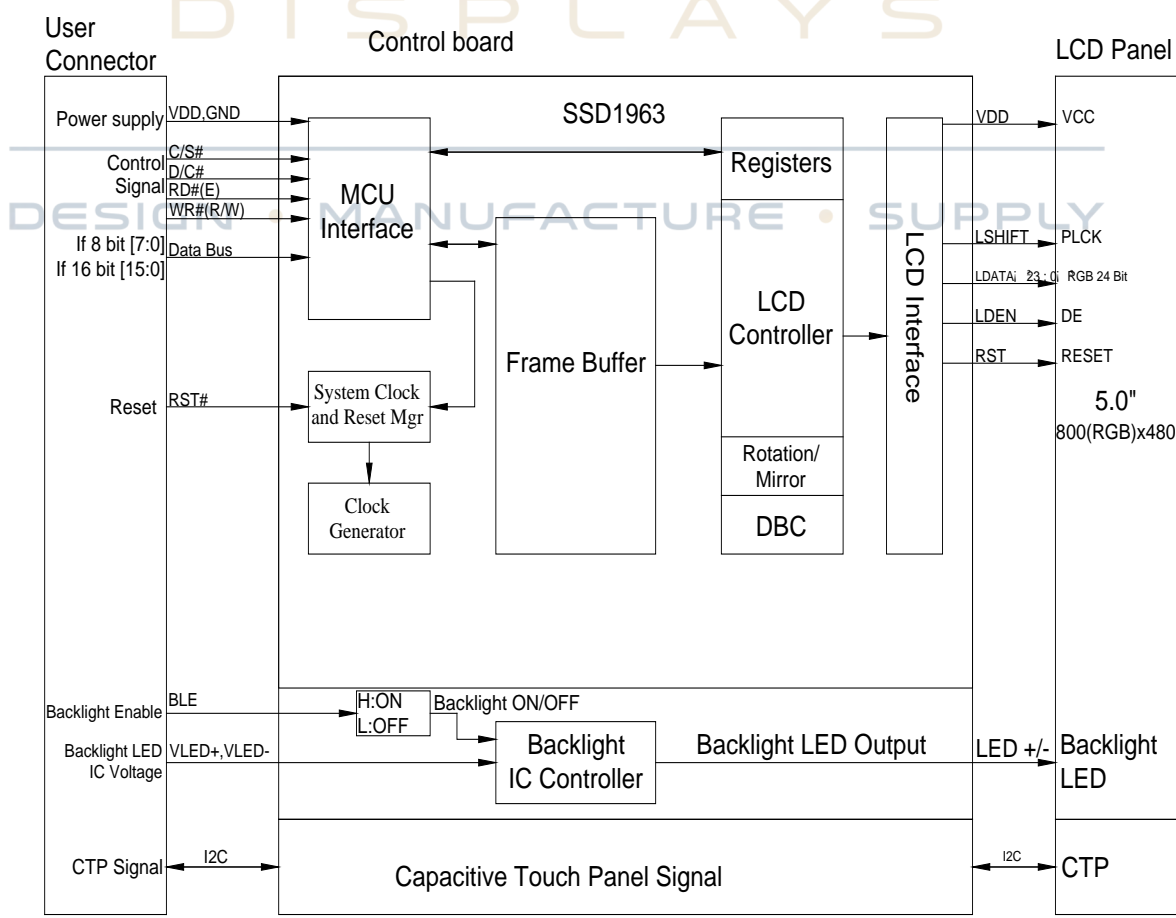
Pin	Symbol	Function	Remark
1	GND	System round pin of the IC. Connect to system ground.	
2	VDD	Power Supply : +3.3V	
3	BL_E	Backlight control signal , H: On \ L: Off	
4	D/C	Data/Command select	
5	WR	Write strobe signal	
6	RD	Read strobe signal	
7	DB0	Data bus	
8	DB1	Data bus	
9	DB2	Data bus	
10	DB3	Data bus	
11	DB4	Data bus	
12	DB5	Data bus	
13	DB6	Data bus	
14	DB7	Data bus	
15	DB8	Data bus (When select 8bits mode, this pin is NC)	Note1
16	DB9	Data bus (When select 8bits mode, this pin is NC)	Note1
17	DB10	Data bus (When select 8bits mode, this pin is NC)	Note1
18	DB11	Data bus (When select 8bits mode, this pin is NC)	Note1
19	DB12	Data bus (When select 8bits mode, this pin is NC)	Note1
20	DB13	Data bus (When select 8bits mode, this pin is NC)	Note1
21	DB14	Data bus (When select 8bits mode, this pin is NC)	Note1
22	DB15	Data bus (When select 8bits mode, this pin is NC)	Note1
23	NC	No connection	
24	CTP_INT	External interrupt to the host	
25	CS	Chip select	
26	RST	Hardware reset	
27	NC	No connection	
28	NC	No connection	
29	CTP_SCL	I2C clock input	
30	CTP_SDA	I2C data input and output	
31	CTP_RST	External Reset, Low is active	
32	NC	No connection	
33	VLED-	VLED- for B/L LED inverter (GND)	
34	VLED-	VLED- for B/L LED inverter (GND)	
35	VLED+	VLED+ for B/L LED inverter	
36	VLED+	VLED+ for B/L LED inverter	

Note1: When select 8bit mode, DB0~DB7 be used, DB8~DB15 no connect
When select 16bit mode, DB0~DB15 be used

Contour Drawing



Block Diagram



Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	TOP	-20	—	+70	°C
Storage Temperature	TST	-30	—	+80	°C

Note: Device is subject to be damaged permanently if stresses beyond those absolute maximum ratings listed above

- Temp. $\leq 60^{\circ}\text{C}$, 90% RH MAX. Temp. $> 60^{\circ}\text{C}$, Absolute humidity shall be less than 90% RH at 60°C

Electrical Characteristics

Operating conditions: (CON3.Pin1=GND, Pin2=VDD)

Item	Symbol	Condition	Min	Typ	Max	Unit	Remark
Supply Voltage For LCM	VDD	—	3.0	3.1	3.3	V	-
Supply Current For LCM	IDD	—	—	150	230	mA	Note1

Note 1 : This value is test for VDD =3.3V , Ta=25°C only

Backlight driving conditions (CON3.Pin33,34=VLED-, Pin35,36=VLED+)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Remark
Operation Current For LED Driver	VLED=5V	200	-	300	mA	Note 1,2
Supply Voltage For LED Driver	VLED+	—	5	—	V	
LED Life Time		—	50,000	-	Hr	Note 2,3,4

Note 1 : Base on VLED=5.0V for the back light driver IC specification

Note 2 : Ta = 25 °C

Note 3 : Brightness to be decreased to 50% of the initial value

Note 4 : The single LED lamp case

DC CHARATERISTICS

Parameter	Symbol	Rating			Unit	Condition
		Min	Typ	Max		
Low level input voltage	V _{IL}	0	-	0.3VDD	V	
High level input voltage	V _{IH}	0.7VDD	-	VDD	V	

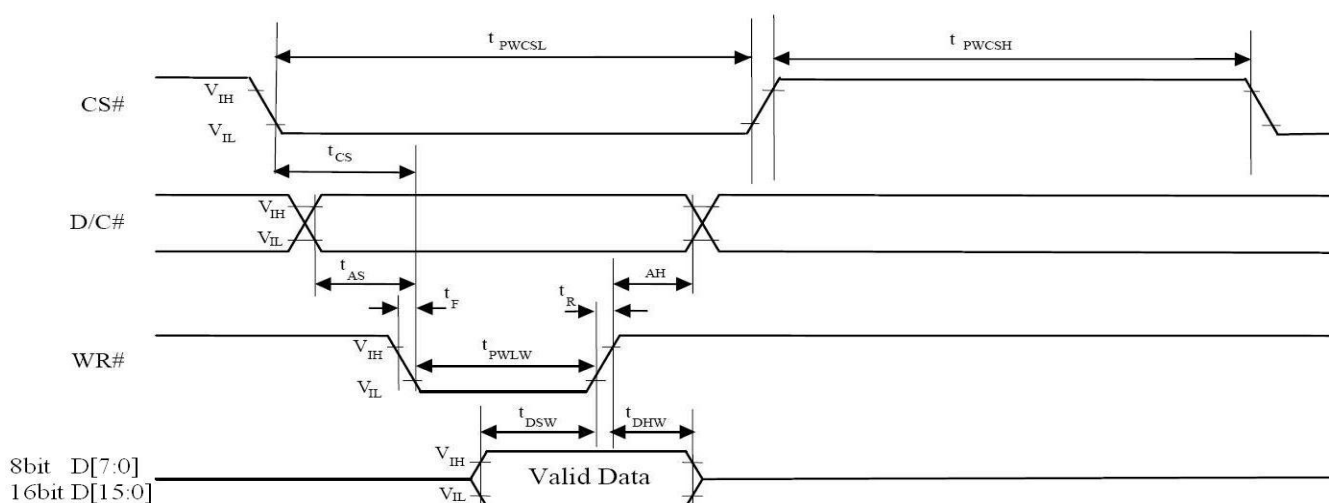
8080 Mode 8bit/16bit

The 8080 mode MCU interface consist of CS#, D/C#, RD#, WR#, Data Bus signals. This interface use WR# to define a write cycle and RD# for read cycle. If the WR# goes low when the CS# signal is low, the data or command will be latched into the system at the rising edge of WR#. Similarly, the read cycle will start when RD# goes low and end at the rising edge of RD#.

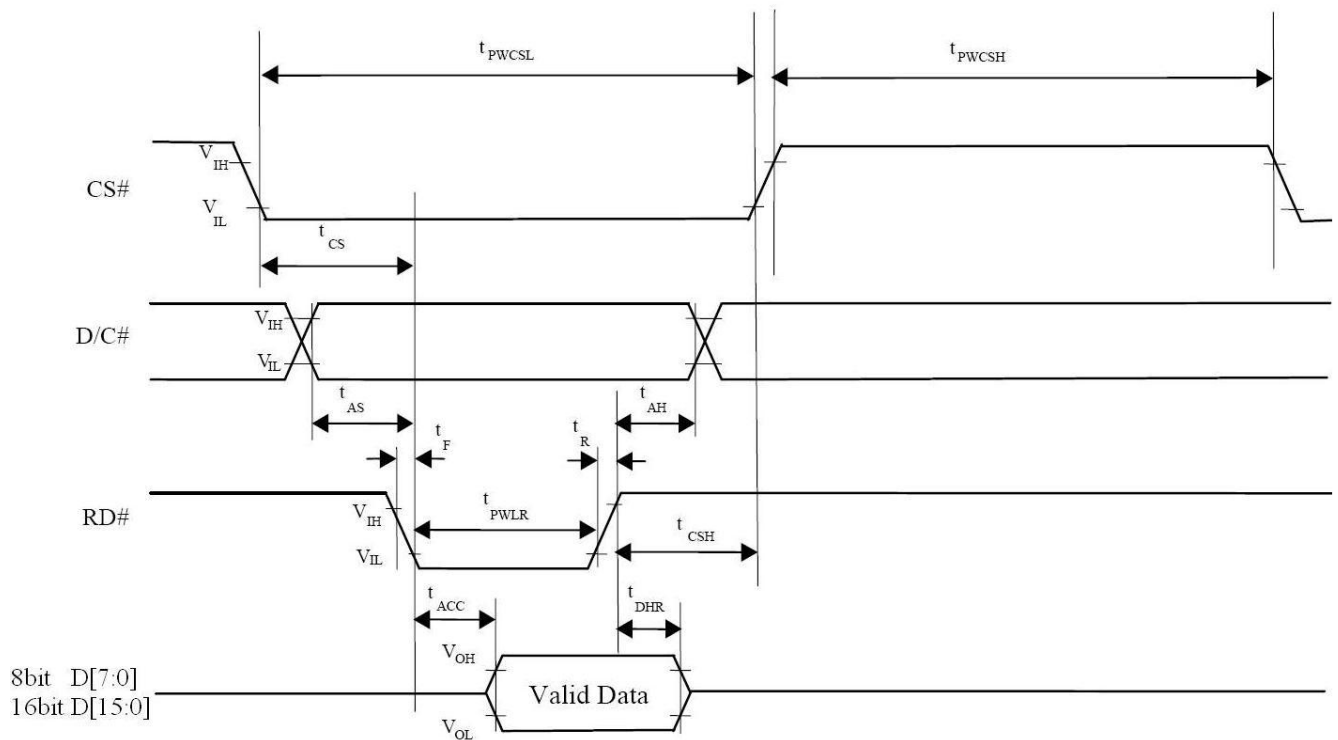
8080 Mode Write Cycle

Symbol	Parameter	Min	Typ	Max	Unit
fMCLK	System Clock Frequency	1	-	110	MHz
tMCLK	System Clock Period	1/ fMCLK	-	-	ns
tPWCSH	Control Pulse High Width Write Read	13 30	1.5* tMCLK 3.5* tMCLK	-	ns
tPWCSL	Control Pulse Low Width Write (next write cycle) Write (next read cycle) Read	13 80 80	1.5* tMCLK 9* tMCLK 9* tMCLK	-	ns
tAS	Address Setup Time	1	-	-	ns
tAH	Address Hold Time	2	-	-	ns
tDSW	Write Data Setup Time	4			ns
tDHW	Write Data Hold Time	1	-	-	ns
tPWLW	Write Low Time	12			ns
tDHR	Read Data Hold Time	1	-	-	ns
tACC	Access Time	32			ns
tPWLR	Read Low Time	36	-	-	ns
tR	Rise Time	-		0.5	ns
tF	Fall Time	-	-	0.5	ns
tCS	Chip select setup time	2		-	ns
tCSH	Chip select hold time to read signal	3	-	-	ns

Parallel 8080-series Interface Timing Diagram(Write Cycle)



Parallel 8080-series Interface Timing Diagram(Read Cycle)



Pixel Data Format

Interface	Cycle	D[15]	D[14]	D[13]	D[12]	D[11]	D[10]	D[9]	D[8]	D[7]	D[6]	D[5]	D[4]	D[3]	D[2]	D[1]	D[0]
16 bits (565 format)	1 st	R5	R4	R3	R2	R1	G5	G4	G3	G2	G1	G0	B5	B4	B3	B2	B1
16 bits	1 st	R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0
	2 nd	B7	B6	B5	B4	B3	B2	B1	B0	R7	R6	R5	R4	R3	R2	R1	R0
	3 rd	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0
8 bits	1 st									R7	R6	R5	R4	R3	R2	R1	R0
	2 nd									G7	G6	G5	G4	G3	G2	G1	G0
	3 rd									B7	B6	B5	B4	B3	B2	B1	B0

Optical Characteristics

Item		Symbol	Condition.	Min	Typ.	Max.	Unit	Remark
Response time		Tr	$\theta=0^{\circ}$ 、 $\Phi=0^{\circ}$	-	10	20	.ms	Note 3
		Tf		-	15	30	.ms	
Contrast ratio		CR	At optimized viewing angle	400	500	-	-	Note 4
Color Chromaticity	White	Wx	$\theta=0^{\circ}$ 、 $\Phi=0$	0.26	0.31	0.36		Note 2,6,7
		Wy		0.28	0.33	0.38		
Viewing angle	Hor.	ΘR	$CR \geq 10$	-	75	-	Deg.	Note 1
		ΘL		-	75	-		
	Ver.	ΦT		-	75	-		
		ΦB		-	75	-		
Brightness		-	-	250	300	-	cd/m ²	Center of display
Uniformity		(U)	-	75	-	-	%	Note5

Ta=25±2℃

Note 1: Definition of viewing angle range

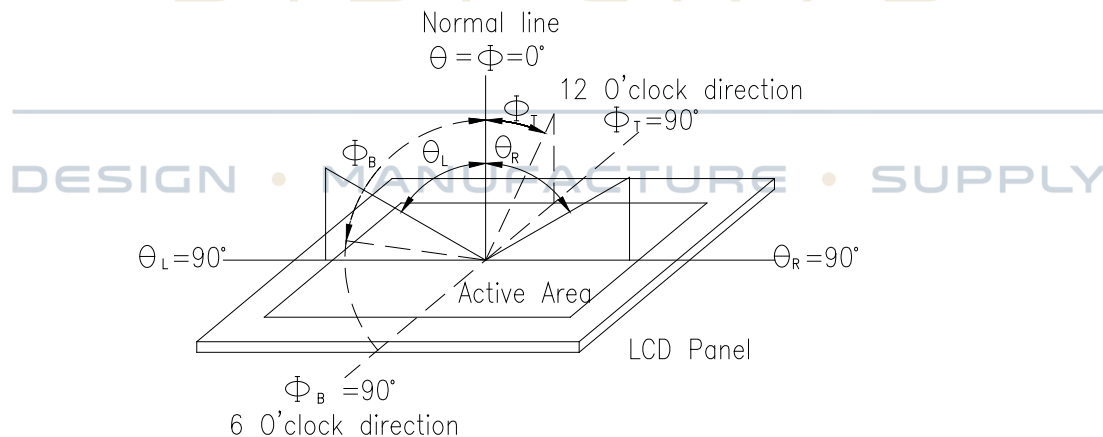


Fig. 11.1. Definition of viewing angle

Note 2: Test equipment setup:

After stabilizing and leaving the panel alone at a driven temperature for 10 minutes, the measurement should be executed. Measurement should be executed in a stable, windless, and dark room. Optical specifications are measured by Topcon BM-7or BM-5 luminance meter 1.0° field of view at a distance of 50cm and normal direction.

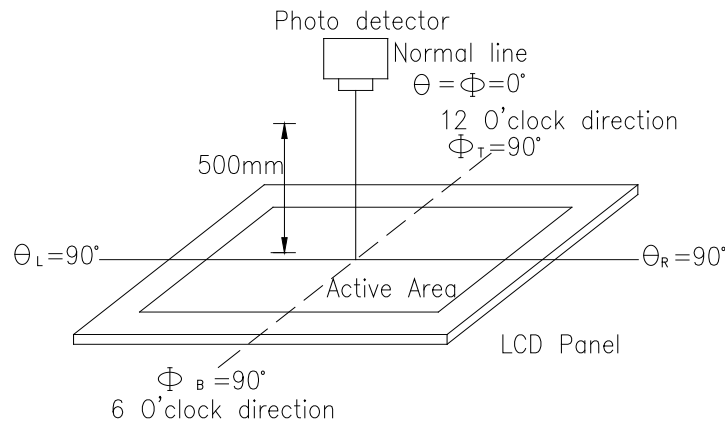
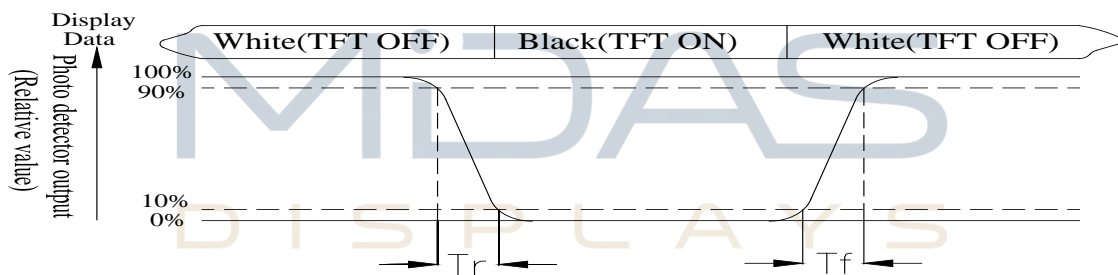


Fig. 11.2. Optical measurement system setup

Note 3: Definition of Response time:

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time, T_r , is the time between photo detector output intensity changed from 90% to 10%. And fall time, T_f , is the time between photo detector output intensity changed from 10% to 90%



Note 4: Definition of contrast ratio:

The contrast ratio is defined as the following expression.

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD on the "White" state}}{\text{Luminance measured when LCD on the "Black" state}}$$

Note 5: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (reference the picture in below). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity (U) = $L_{\min}/L_{\max} \times 100\%$

L = Active area length

W = Active area width

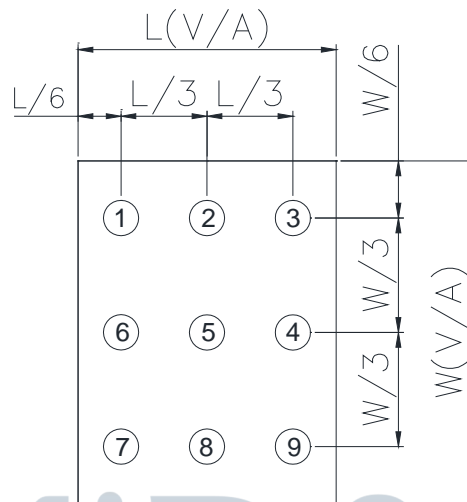


Fig.11.3. Definition of uniformity

Note 6: Definition of color chromaticity (CIE 1931)

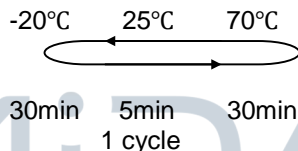
Color coordinates measured at the center point of LCD

Note 7: Measured at the center area of the panel when all the input terminals of LCD panel are electrically opened.

DESIGN • MANUFACTURE • SUPPLY

Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test			
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	—
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation 	-20°C/70°C 10 cycles	—
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact) ,±800v(air), RS=330Ω CS=150pF 10 times	—

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

The drawing illustrates the mechanical specifications of the MIDAS module. It includes three views: a top view showing the overall footprint and internal layout, a front view showing the module's profile, and a back view showing the component arrangement and adhesive layers. Key dimensions include the total footprint of 75.20x115.70 mm, the sensor area of 66.10x46.20 mm, and the thickness of the cover glass (0.70 mm) and TTD glass (0.70 mm). The drawing also specifies the use of TESA4982 adhesive (T=0.1mm) and the presence of a pull tape. A pinout table is provided for the 10-pin connector.

PIN	Logic
1	VSS
2	VDDT
3	SCL
4	NC
5	SDA
6	NC
7	/RST
8	NC
9	/INT
10	VSS

MIDAS
DISPLAYS

DESIGN • MANUFACTURE • SUPPLY